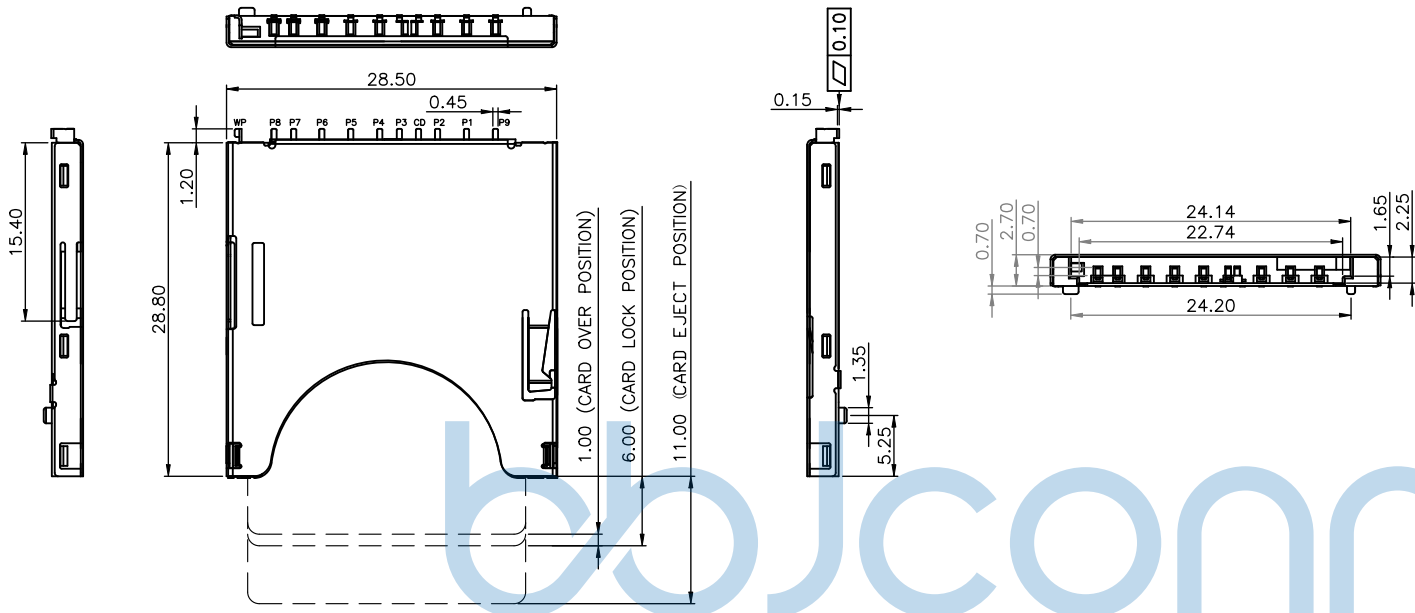


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



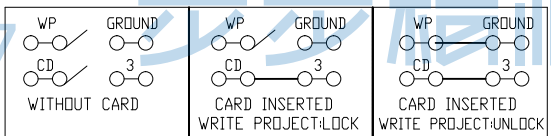
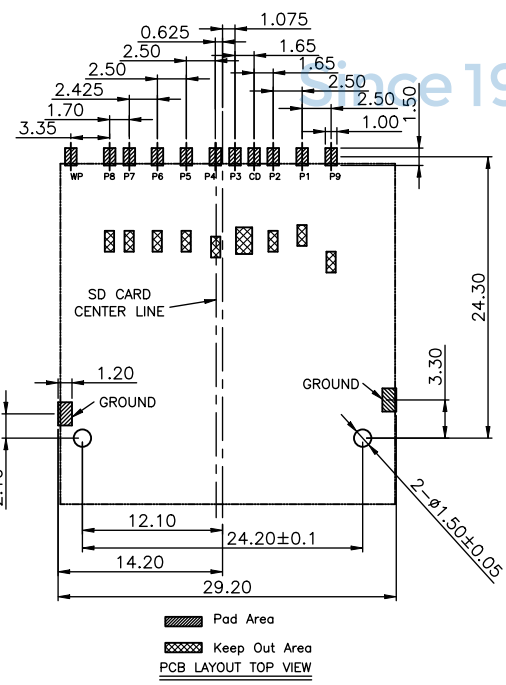
***Electrical Characteristics:**
 Contact Current Rating: 0.5 Amperes.
 Dielectric Withstanding Voltage: AC500V r.m.s.
 Insulation Resistance: 1000 MΩ Minimum.
 Contact Resistance: 100 mΩ Maximum.

***Environmental:**
 Operating Temperature: -25°C~+90°C.

***Environmental:**
 Mating Cycles: 5000~10,000 Insertions.

***Mechanical Characteristics:**
 Card Push Insertion/Out Force: 1.4kgf. MAX
 Contact Separation Force: 0.20kgf Minimum.

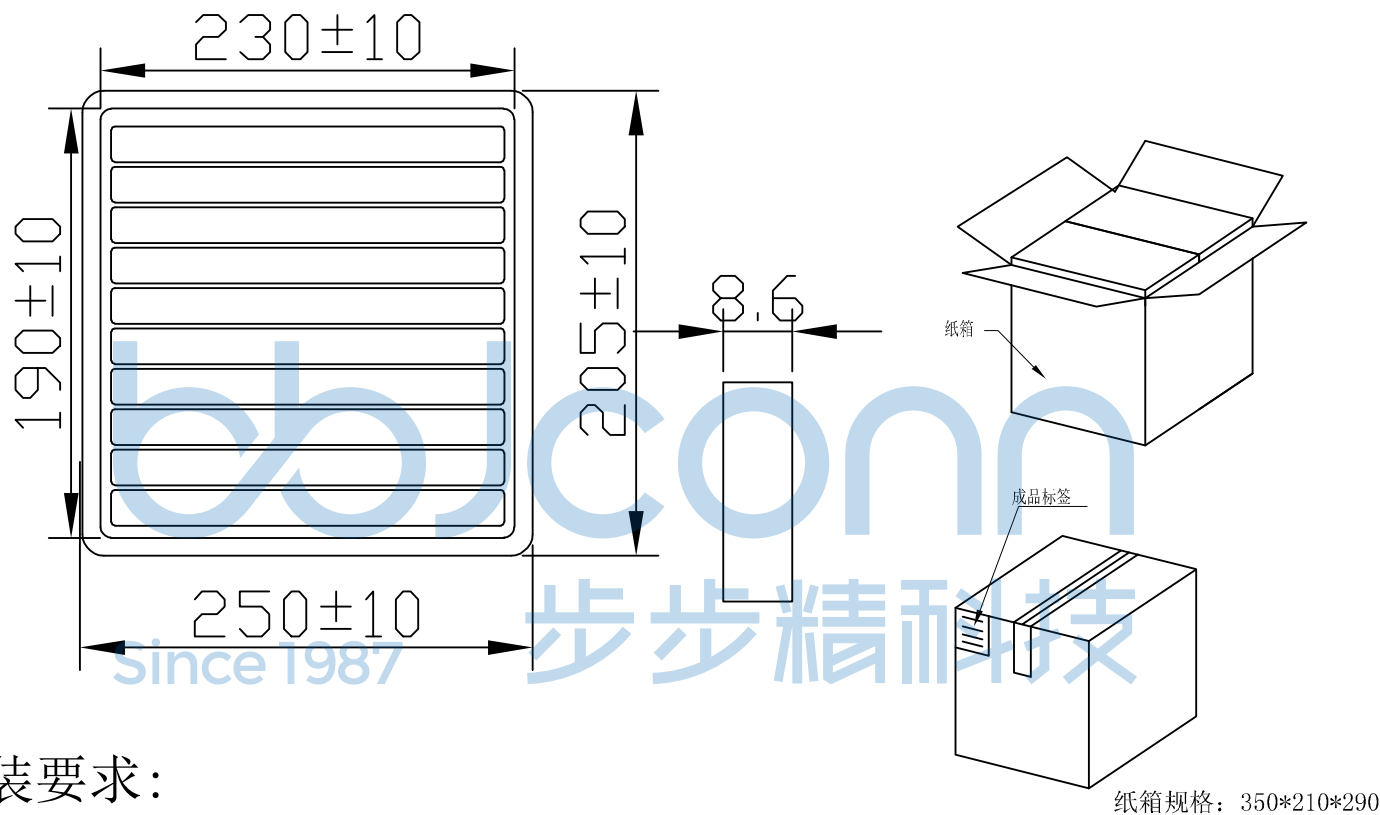
***Material:**
 Insulator: HI-Temp Plastic UL 94V-0 Rated.
 Contact: Copper Alloy(t=0.15mm).
 Shell: Stainless Steel(t=0.20mm).
 Spring: SWP.



SD CARD PIN DESIGN			
Pin#	Name	Type	Card Detect/ Date Line[Bit3]
1	CD/DAT3	I/O/PP	Command/Response
2	CMD	PP	Supply voltage
3	Vss1	S	Supply voltage ground
4	VDD	S	Supply voltage
5	CLK	I	Clock
6	Vss2	S	Supply voltage ground
7	DAT0	I/O/PP	Date Line [Bit0]
8	DAT1	I/O/PP	Date Line [Bit1]
9	DAT2	I/O/PP	Date Line [Bit2]



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	.X: ±0.38 .XX: ±0.25 .XXX: ±0.13	X': ±3' X'': ±2' XX': ±1'	NAME: 卡座 SD PUSH 定位片向内 9P H=2.70 贴片 带柱
	APPD. JM_Zheng CHKD. LYX	PJ. NO.: CD.03.01-02-0004 SIZE: A4 DRW NO.:	FINISH: SEE NOTES MAT'L.: SEE NOTES
	DR. TSP	SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2	



1. 包装要求:
- 1.1 每盒吸塑盒包装40pcs;
 - 1.2 每25盘放一箱, 共计1000PCS;
 - 1.3 纸箱外贴上标签。

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APPD.	JM_Zheng	PJ. NO.: CD.03.01-02-0004 SIZE: A4 DRW NO.:		FINISH: SEE NOTES MAT'L.: SEE NOTES	
CHKD.	LYX	SCALE: N/A		REV.: A0	UNIT: mm
PDWG.NO:	0214-1	DR.	TSP	PAGE: 2/2	